

EAST - (10710510 support structure for lid and active regions vsp:1)

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5		Shinozaki	US 20040007778 A	2004	41 Semiconductor integrated circuit dev	257/75	257/728.0						US 20040
6		Shimoishiz	US 20010033021 A	2001	16 Semiconductor device and method for	257/737	257/724						US 200100
7		Rogers, Hnr	US 6888253 B1	2005	7 Inexpensive wafer level MIMC chip pac	257/774	257/758						US 68882
8		Katagiri, Hi	US 6867123 B2	2005	72 Semiconductor integrated circuit dev	438/61	257/758						US 686712
9		Matsunaga	US 6864583 B2	2005	18 Wiring structure of semiconductor dev	257/75	257/758						US 68645
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